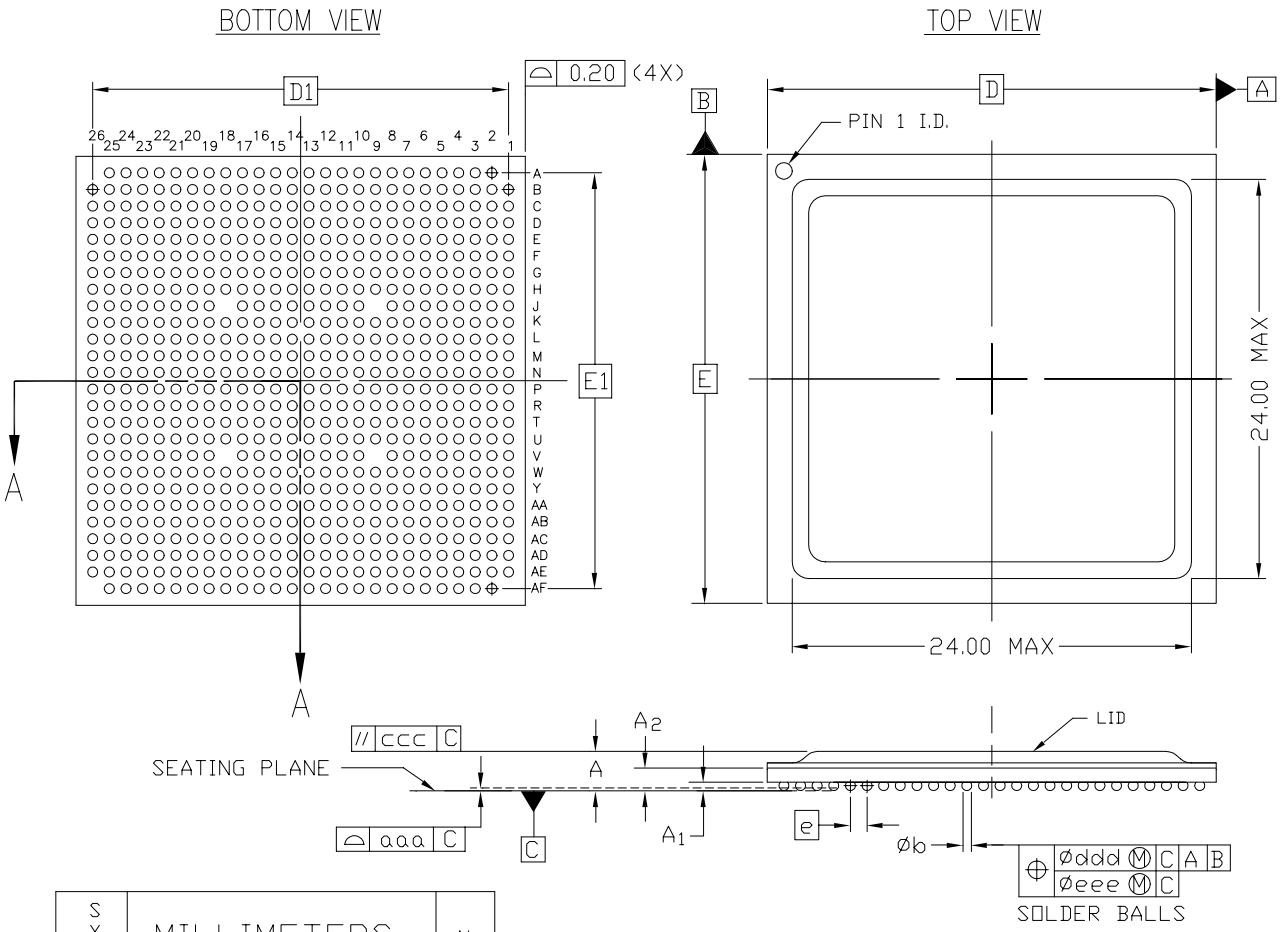
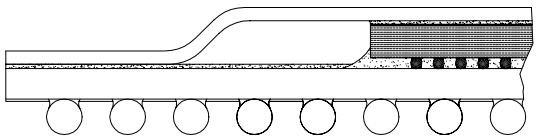
Flip Chip BGA (FF668) Package



SYMBOL	MILLIMETERS			NOTE
	MIN.	NOM.	MAX.	
A		2.65	2.85	
A_1	0.40	0.50	0.60	
A_2	1.10	1.25	1.40	
D/E	27.00 BASIC			
D_1/E_1	25.00 REF			
e	1.00 BASIC			
øb	0.50	0.60	0.70	
aaa			0.20	
ccc			0.25	
ddd			0.25	
eee			0.10	
M	26			2



SECTION A–A
(NOT TO SCALE)

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M–1994
2. SYMBOL 'M' IS THE BALL MATRIX SIZE.
3. CONFORMS TO JEDEC MS–034–AAL–1 (DEPOPULATED)

668–BALL FLIP CHIP BGA (FF668)

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